

J. ERNEST KENNEY
EUGENE MAR
RICHARD E. FICHTER
THOMAS J. MOORE
JOSEPH DEBENEDECTIS*
BENJAMIN E. URCIA*
WONKI PARK*

GEORGE CHUNG CHIN CHEN*

* BAR OTHER THAN VA.
* REG. PATENT AGENT

LAW OFFICES

BACON & THOMAS, PLLC

625 SLATERS LANE - FOURTH FLOOR
ALEXANDRIA, VIRGINIA 22314-1176

U.S.A.

TELEPHONE
(703) 683-0500

FACSIMILE
(703) 683-1080
(703) 683-0884

E-Mail
mail@baconthomas.com

FACSIMILE COMMUNICATION

FAX RECEIVED

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GROUP 370

To: Mr. Omar Flores-Sanchez
Group Art Unit: 3724

Fax #: (703) 305-3579
(703) 872-9302

Re: U.S. Patent Application No. 09/394,918

Inventor: J. SU

From: Wonki K. Park
Associate Attorney

Total pages: 2 including the cover sheet

Date: February 6, 2002

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Thank you, BACON & THOMAS, PLLC.

Message:

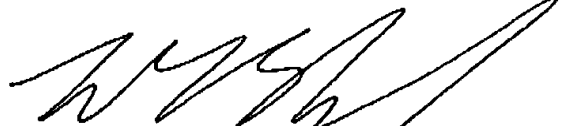
Thank you for the courteous interview held on January 29, 2002. During the interview we discussed claim 7, and in particular we discussed page 3, second full paragraph of my amendment and response filed on January 25, 2002.

As is noted in the interview summary, you indicated that if claim 7 is amended to add language that distinguishes over the reference to Shimizu et al., the application will be reviewed favorably. We also agreed in the interview that the use of the reference to Shimizu et al. under 35 U.S.C. 102 (a) is improper.

Please review the attached proposed new claim 13 (DRAFT) which will replace claim 7. Claims 9-12 will be amended to depend from claim 13 if claim 13 is deemed allowable. Please promptly let me know if you believe further amendments are necessary. Claim 13 recites language which illustrates the inventive subject matter that clearly distinguishes over the Shimizu et al. reference. The bold-type highlights some of the differences between claim 13 and the Shimizu et al. reference.

At your convenience, you can reach me at (703) 683-0500.

Thank you for your kind attention to this matter.



WONKI K. PARK

DRAFT**PATENT**
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Jau-Yuen SU

Group Art Unit: 3724

Serial No.: 09/394,918

Examiner: O. Flores-Sanchez

Filed: September 13, 1999

Atty. Dkt.: SUJA3001/REF/WKP

For: PROCESS FOR SAWING SUBSTRATE STRIP

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**PROPOSED NEW CLAIM 13 WHICH WILL BE SUBSTITUTED FOR CLAIM 7
(FOR DISCUSSION PURPOSED ONLY)**

13. (New) A process for sawing a substrate strip having a plurality of substrate areas by a saw machine, wherein the substrate has a longitudinal axis and a lateral axis and the substrate areas are grouped along the longitudinal axis, the process comprising the steps of:

providing a plurality of alignment marks around each of the individual substrate areas on the substrate strip;

providing a plurality of cutting marks around the substrate areas on the substrate strip such that two opposing longitudinal rows of the cutting marks are provided along the longitudinal axis of the substrate and two opposing lateral rows of the cutting marks are provided along the lateral axis with the substrate areas positioned between the longitudinal and lateral rows of the cutting marks;

positioning the saw machine with respect to a first substrate area according to the alignment marks of the first substrate area along the longitudinal axis and cutting the substrate strip on cutting tracks defined between respective ones of the cutting marks parallel to the lateral axis; and

repositioning the saw machine with respect to an adjacent one of the substrate areas and cutting the substrate strip according to the step of positioning the saw machine, whereby cutting error that results from each substrate area will not accumulate to the adjacent substrate area.